



PCN# : P561AAB
Issue Date : Jul. 22, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 20, 2015

Expected First Date Code of Changed Product :1543

Description of Change (From) :
Manufacturing assembly and test site in Yangxin City, Shandong Province,China.

Description of Change (To) :
Manufacturing assembly and test site in Wuxi City, Jiangsu Province, China.

Item	From	To
Assembly and test site	Yangxin City, Shandong Province	Wuxi City, Jiangsu Province
Wafer sourcing	I-lan, Taiwan	Kaohsiung, Taiwan
Die attach material	Solder Paste Pb92.5Sn5Ag2.5	Solder Paste Pb92.5Sn5Ag2.5
Wire bond material	Clip bonding	Clip bonding
Leadframe material	KFC,HCL-12S	Copper Alloy
EMC material	EME-1100SA	ELL2KS200

Reason for Change:
Site transfer is to improve the capacity and delivery support. This change will have no impact on product quality reliability electrical visual or mechanical performance and affected products will remain fully compliant to all published

specifications.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your company's procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR2560CT	TT220	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR1060	TT220	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR760	TT220	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR4060PT	TT247	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR3035PT	TT247	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77

Qualification Plan	Device	Package	Process	No. of Lots
Q20110296B	MBR3060PT	TT247	Schottky	1

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Humidity Bias Test	85%RH, 85C, 80% BV	JESD22-A101B	1000 hrs	0/77
High Temperature Reverse Bias Test	150C, 80% BV	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Power Cycle	Delta 100C, 5 Min cycle	MIL-STD-750-1036	6000 cyc	0/77
Temperature Cycle	-55C, 150C	JESD22-A104	1000 cyc	0/77